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(54) Title: ELECTROCHEMICAL-MECHANICAL POLISHING COMPOSITION AND METHOD FOR USING THE SAME

(57) Abstract: The invention provides an electrochemical-mechanical polishing composition comprising: (a) a chemically inert, water-soluble salt, (b) a corrosion inhibitor, (c) a polyelectrolyte, (d) a complexing agent, (e) an alcohol, and (f) water. The invention also provides a method of polishing a substrate comprising one or more conductive metal layers, the method comprising the steps of: (a) providing a substrate comprising one or more conductive metal layers, (b) immersing a portion of the substrate in an electrochemical-mechanical polishing composition, the polishing composition comprising: (i) a chemically inert, water-soluble salt, (ii) a corrosion inhibitor, (iii) a polyelectrolyte, (iv) a complexing agent, (v) an alcohol, and (vi) water, (c) applying an anodic potential to the substrate, the anodic potential being applied to at least the portion of the substrate immersed in the polishing composition, and (d) abrading at least a portion of the immersed portion of the substrate to polish the substrate.

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